



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Wang et al.

Attorney Docket No.: KLA1P099

Application No.: 10/691,940

Examiner: Unassigned

Filed: October 22, 2003

Group: Unassigned

Title: VOID CHARACTERIZATION IN METAL
INTERCONNECT STRUCTURES USING X-RAY
EMISSION ANALYSES

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on December 3, 2003 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed: 

Agnes F. Spence

**INFORMATION DISCLOSURE STATEMENT
37 CFR §§1.56 AND 1.97(b)**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, copies of which are attached, may be material to examination of the above-identified patent application. Applicants submit these references in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make these references of official record in this application.

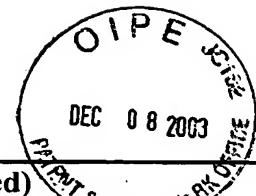
This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that these references indeed constitute prior art.

This Information Disclosure Statement is filed within three (3) months of the filing date of the above-referenced application. Accordingly, it is believed that no fees are due in connection with the filing of this Information Disclosure Statement. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. KLA1P099).

Respectfully submitted,
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Form 1449 (Modified)

Information Disclosure
Statement By Applicant

(Use Several Sheets if Necessary)

Atty Docket No.

Application No.:

KLA1P099
10/691,940

Applicant:

KLA-Tencor

Filing Date

Group
Unassigned

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A	5,877,498	03/02/99	Sugimoto et al.			07/15/97
	B	5,900,645	05/04/99	Yoshinki Yamada			11/21/97
	C	6,351,516	02/26/02	Mazor et al.			12/14/99
	D						
	E						
	F						
	G						
	H						
	I						

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	O	Amekura, Hiroshi et al., <i>X-Ray Emission Induced by 60 keV High-Flux Copper Negative-Ion Implantation</i> , February 2001, Japan Society of Applied Physics.
	P	Shaw, Judy B. et al., <i>Voids, Pits, and Copper</i> , Winter 2002, Yield Management Solutions: Cu/low Special Focus.
	Q	Testoni, A.L., <i>CuVA: Analyzing Voids in Cu Interconnects</i> , June 20, 2002, KLA-Tencor Progress Report.
Examiner		Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.